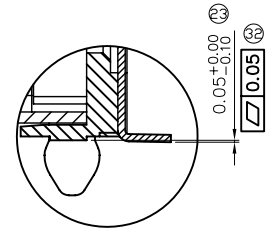
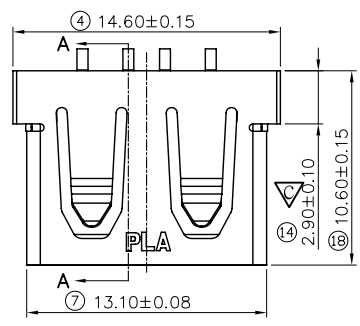
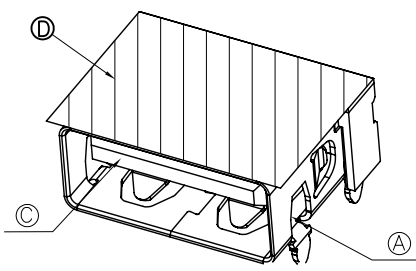
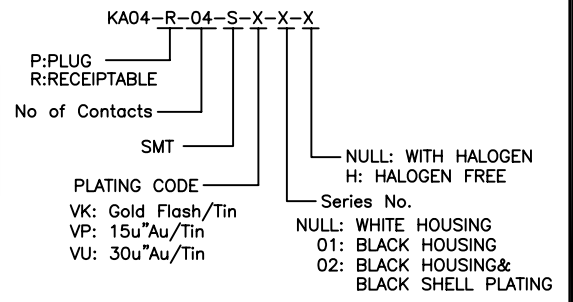


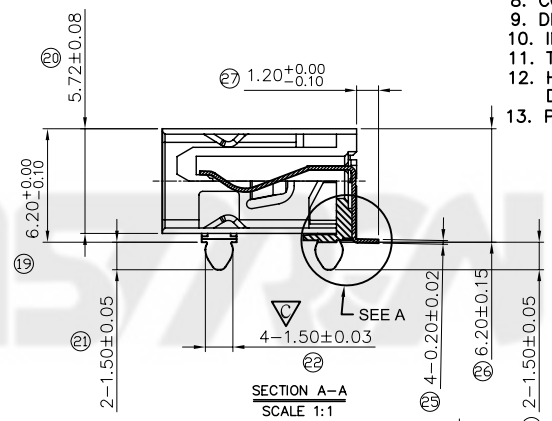
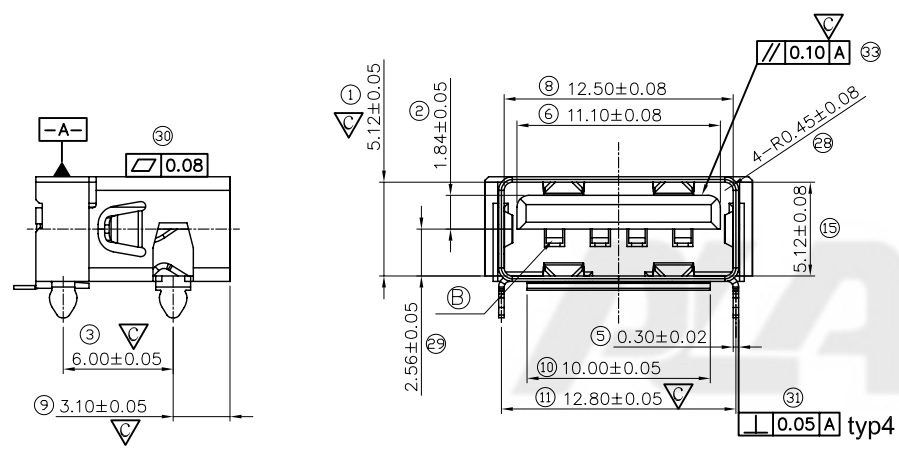
REV.	ECN No.	Description	Designer/date
9	CH12050251	UPDATE DRAWING	Kevin_05/23'12
10	EH13050026	MODIFY THE LAYOUT	Ian Lui_05/19'13

NOTES: (UNLESS OTHERWISE SPECIFIED)

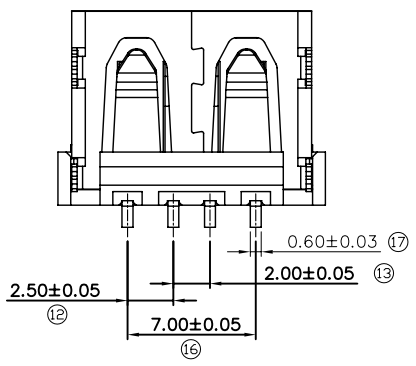
- DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994
- HOUSING: THERMOPLASTIC, UL94V-2, COLOR: WHITE/BLACK
- FEATURES:
 - CONTACT: PHOSPHOR BRONZE C5191R-H, T=0.20±0.05mm, GOLD PLATED 30u" Min ON CONTACT AREA, 150u" Min TIN (LEAD FREE) ON SOLDER AREA, 50-100u" NICKEL UNDERPLATED.
 - SHELL: PHOSPHOR BRONZE C5191R-H, T=0.30±0.05mm, 30~80u" MIN BRIGHT NICKEL PLATING OVER ALL, NICKEL MUST BE SOLDRABILITY.
- TOTAL MATING FORCE: 35N Max.
- TOTAL UNMATING FORCE: Initial to 5000 cycles: 10N min.
- DURABILITY: 5000 MATING CYCLES Min.
- VOLTAGE RATING: 30V AC.
- CURRENT RATING: 1.5 AMPERE.
- CONTACT RESISTANCE: 30 mohms MAX. FOR INITIAL.
- DIELECTRIC WITHSTANDING VOLTAGE: 500V AC/MINUTE.
- INSULATION RESISTANCE: 1000 Megohms MIN..
- TEMPERATURE RANGE: 0°~50°
- HARMFUL MATERIAL SHOULD BE COMPLIANT TO DOC. "EI-0005" STANDARDS.
- PRODUCT MATRIX:



DETAIL A
SCALE 2:1



SECTION A-A
SCALE 1:1



Ⓐ	SHELL	COPPER ALLOY	1 PCS
Ⓑ	USB CONTACT	COPPER ALLOY	1 SET
Ⓒ	HOUSING	HIGH TEMPERATURE THERMOPLASTIC	1 PCS
Ⓓ	FILM	MALAY	1 PCS
	PART NAME	MATERIAL	Q'TY



GENERAL TOLERANCE		SCALE 1:1	ORIGINAL DRAWN Jin.Guo	DATE 04/24'08	DWG. NO. 600-0000-0381	TITLE	REV. 10
XX ±	XXX ±	UNIT MM	CHECK ---	DATE ---	PARTS NO.(INTENDED USE) KA04-R-04-S-X-* Series	CUSTOMER DRAWING	SHEET 1/1
X ± 0.30	.XXX ±	SIZE A4	APPROVE Lane Sun	DATE 05/23'12			
.X ± 0.25	X.* ± 3°						
.XX ± 0.20	.X.* ± 2°						